# 2SD1030

# Silicon NPN epitaxial planer type

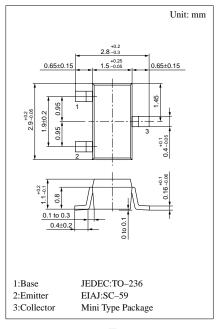
### For low-frequency amplification

### Features

- High foward current transfer ratio h<sub>FE</sub>.
- Low collector to emitter saturation voltage V<sub>CE(sat)</sub>.
- $\bullet~$  High emitter to base voltage  $V_{EBO}.$
- Low noise voltage NV.
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

## Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	$V_{CBO}$	50	V
Collector to emitter voltage	$V_{CEO}$	40	V
Emitter to base voltage	$V_{EBO}$	15	V
Peak collector current	$I_{CP}$	100	mA
Collector current	$I_C$	50	mA
Collector power dissipation	$P_{C}$	200	mW
Junction temperature	Tj	150	°C
Storage temperature	$T_{stg}$	<b>−55 ~ +150</b>	°C



Marking symbol: 1Z

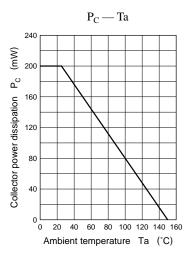
# ■ Electrical Characteristics (Ta=25°C)

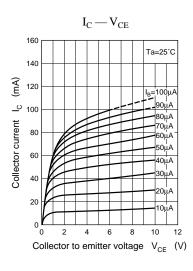
Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	$I_{CBO}$	$V_{CB} = 20V, I_E = 0$			100	nA
	I <sub>CEO</sub>	$V_{CE} = 20V, I_{B} = 0$			1	μА
Collector to base voltage	V <sub>CBO</sub>	$I_{\rm C} = 10 \mu A, I_{\rm E} = 0$	50			V
Collector to emitter voltage	V <sub>CEO</sub>	$I_{\rm C} = 1  \text{mA},  I_{\rm B} = 0$	40			V
Emitter to base voltage	V <sub>EBO</sub>	$I_{\rm E} = 10 \mu A, I_{\rm C} = 0$	15			V
Forward current transfer ratio	h <sub>FE</sub> *	$V_{CE} = 10V, I_{C} = 2mA$	400	1000	2000	
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 10$ mA, $I_B = 1$ mA		0.05	0.2	V
Transition frequency	$f_T$	$V_{CB} = 10V, I_E = -2mA, f = 200MHz$		120		MHz

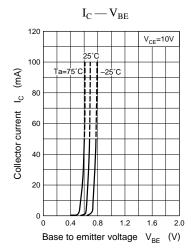
### \*h<sub>FE</sub> Rank classification

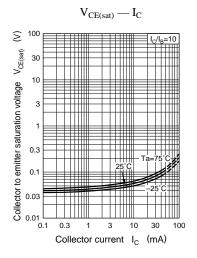
Rank	R	S	T
h <sub>FE</sub>	400 ~ 800	600 ~ 1200	1000 ~ 2000
Marking Symbol	1ZR	1ZS	1ZT

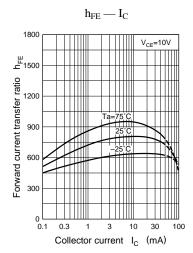
Transistor 2SD1030

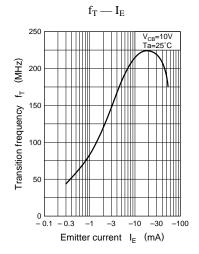


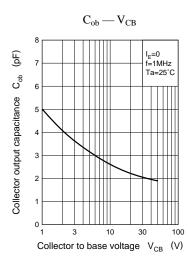












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